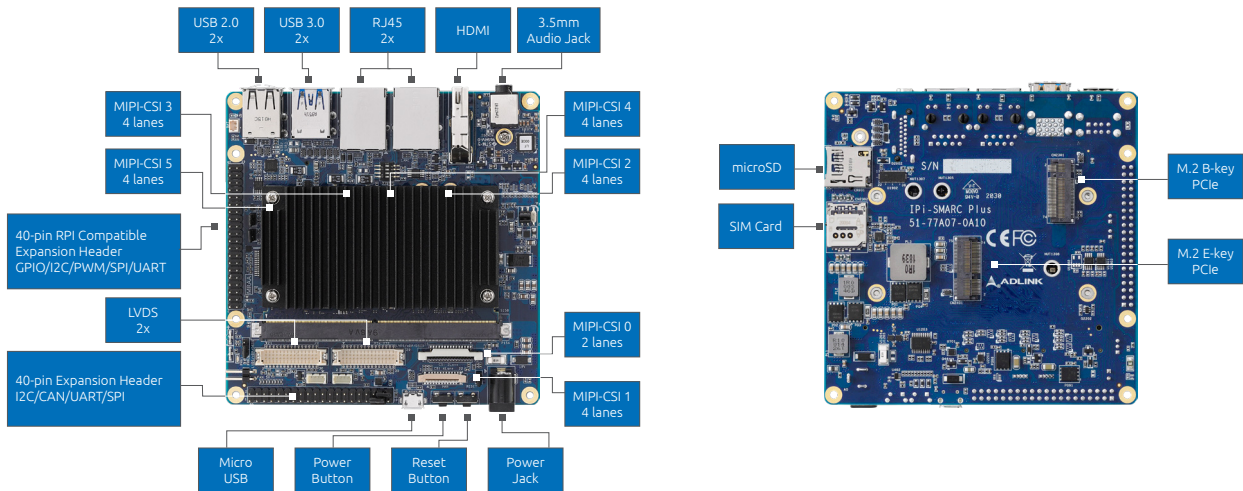


I-Pi SMARC RB5

I-Pi SMARC Plus Prototyping Kit DevKit based on Qualcomm® Robotics RB5 Platform



Features

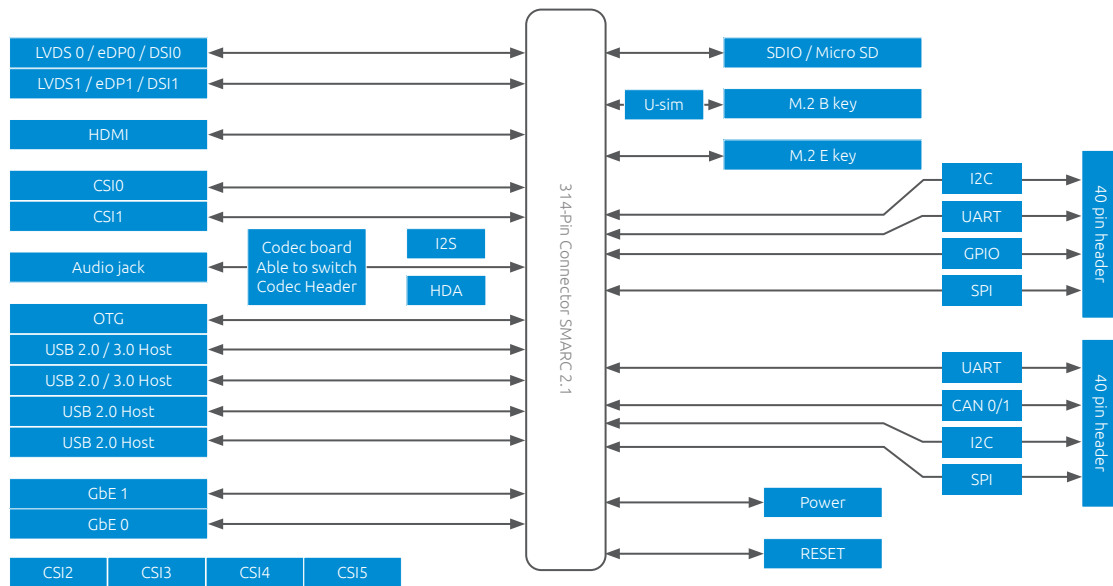
- Based on Qualcomm® QRB5165 SoC with Qualcomm® Kryo™ 585 Octa-core CPU and AI Engine delivering up to 15 TOPS
- Equipped with SMARC 2.1 compatible module specially designed for robotics and AIoT applications requiring long life, high MTBF and strict revision control
- Includes everything needed to go live in minutes
- Industrial grade quality and 10 year product availability
- Supports Ubuntu and Yocto OS

Specifications

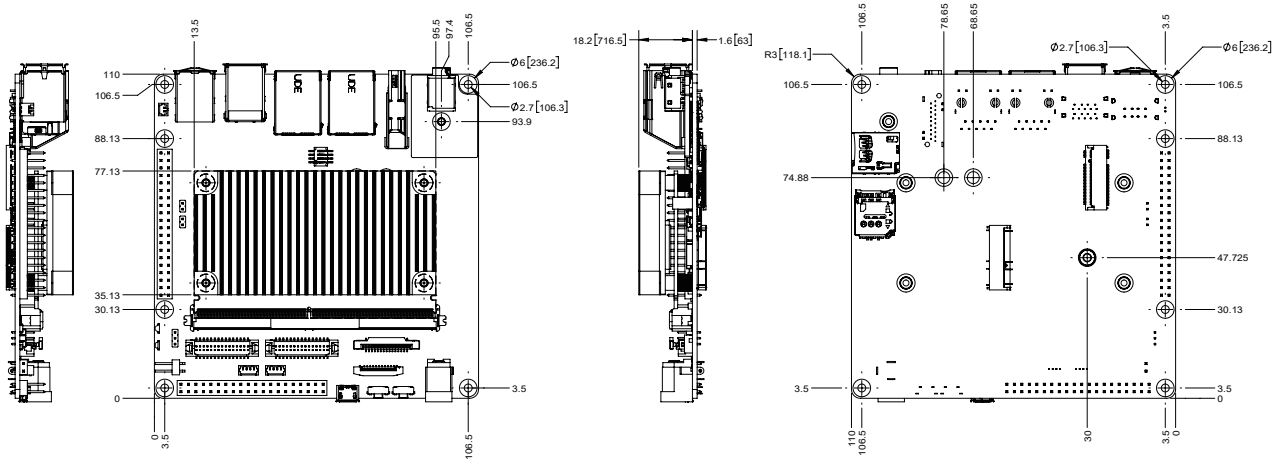
CORE SYSTEM	SoC	Qualcomm® QRB5165 SoC with Kryo™ 585 Octa-core CPU
	NPU	Qualcomm® AI Engine delivering up to 15 TOPS
	Architecture	Arm Cortex-A77
	Memory	8GB LPDDR4
	Storage	128GB UFS
	IoT Security	TPM 2.0 (optional) / Qualcomm® Secure Processing Unit
CONNECTIVITY	Wi-Fi	IEEE 802.11 2X2 MIMO ac/a/b/g/n Wireless LAN (optional)
	Bluetooth	Bluetooth 5.0 compliant with Bluetooth 2.1+EDR (optional)
ETHERNET	LAN	2x GbE
AUDIO	Codec	WM890
VIDEO	GPU Core	Qualcomm® Adreno 650 GPU
	Video Decoding	1080p60 HEVC, H.265 for decode H.264, VP9, VP8
	Video Encoding	1080p60 H.265, H.264
	Camera	5x MIPI-CSI (4 data lanes) 1x MIPI-CSI (2 data lanes)

I/O INTERFACES	40-pin RPI Expansion Header	GPIO / I2C / PWM / SPI / UART
	40-pin Expansion Header	I2C / CAN / SPI / UART
CONNECTORS	Display	1x HDMI 2x LVDS
	Audio	1x 3.5mm Audio Jack
	Network	2x RJ45
	USB	2x USB 3.0 2x USB 2.0 1x Micro USB
	Buttons	1x Reset 1x Power
	SD Card Slot	1x microSD
	SIM Card Slot	1x SIM
POWER	M.2 Card Slots	1x M.2 B-key PCIe 1x M.2 E-key PCIe
	Input	19V+/-5% DC
OPERATING SYSTEMS	Connector	DC Jack
	Standard Support	Ubuntu / Yocto
MECHANICAL AND ENVIRONMENTAL	Form Factor	SGET SMARC Specifications v2.1
	Dimensions	SMARC short size module (82mm x 50mm)
	Operating Temperature	Standard: 0°C to +60°C Rugged: -20°C to +85°C (optional)
	Humidity	5-90% RH operating, non-condensing 5-95% RH storage
	Shock and Vibration	IEC 60068-2-64 and IEC 60068-2-27 MIL-STD-202 F Method 213B, Table 213-I, Condition A Method 214A, Table 214-I, Condition D
	HALT	Thermal Stress, Vibration Stress, Thermal Shock and Combined Test

Functional diagram



Dimensional drawing



Ordering information

- I-Pi SMARC RB5 (EU)
I-Pi SMARC development kit based on LEC-RB5 module including 8GB LPDDR4, 128GB UFS, Micro USB cable and EU AC power adapter

- I-Pi SMARC RB5 (US)
I-Pi SMARC development kit based on LEC-RB5 module including 8GB LPDDR4, 128GB UFS, Micro USB cable and US AC power adapter



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